



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

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We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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HX321LS11IB2K2/16

16GB (8GB 1G x 64-Bit x 2 pcs.) DDR3L-2133
CL11 204-Pin SODIMM Kit



DESCRIPTION

HyperX HX321LS11IB2K2/16 is a kit of two 1G x 64-bit (8GB) DDR3L-2133 CL11 SDRAM (Synchronous DRAM) 2Rx8, low voltage, memory modules, based on sixteen 512M x 8-bit DDR3 FBGA components per module. Total kit capacity is 16GB. Each module kit has been tested to run at DDR3L-2133 at a low latency timing of 11-12-13 at 1.35V or 1.5V. Additional timing parameters are shown in the PnP Timing Parameters section below. The JEDEC standard electrical and mechanical specifications are as follows:

Note: The PnP feature offers a range of speed and timing options to support the widest variety of processors and chipsets. Your maximum speed will be determined by your BIOS.

PnP JEDEC TIMING PARAMETERS:

- DDR3-2133 CL11-12-13 @1.35V or 1.5V
- DDR3-1866 CL10-11-12 @1.35V or 1.5V
- DDR3-1600 CL9-9-10 @1.35V or 1.5V

SPECIFICATIONS

CL(IDD)	11 cycles
Row Cycle Time (tRCmin)	44.22ns (min.)
Refresh to Active/Refresh Command Time (tRFCmin)	260ns (min.)
Row Active Time (tRASmin)	31.875ns (min.)
Maximum Operating Power	TBD W* @1.35V
UL Rating	94 V - 0
Operating Temperature	0° C to 85° C
Storage Temperature	-55° C to +100° C

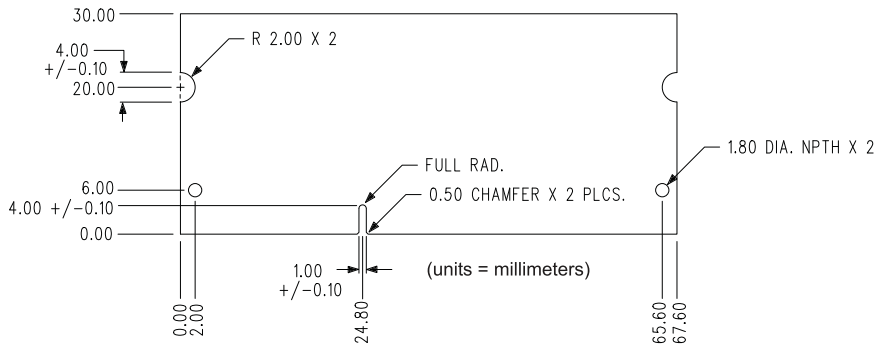
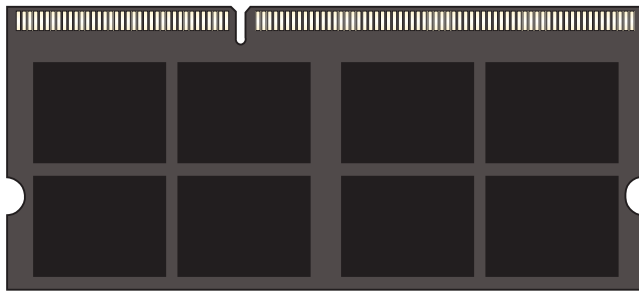
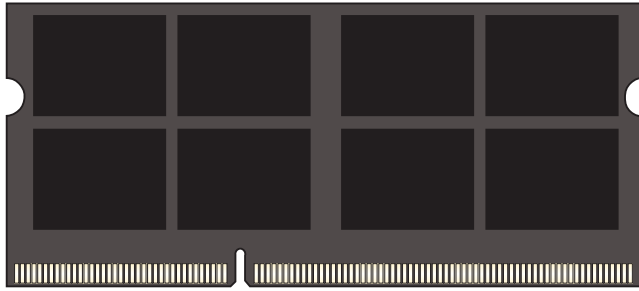
*Power will vary depending on the SDRAM used.

FEATURES

- JEDEC standard 1.35V and 1.5V
- VDDQ = 1.35V and 1.5V
- 1066MHz fCK for 2133Mb/sec/pin
- 8 independent internal bank
- Programmable CAS Latency: 15, 14, 13, 12, 11, 10, 9, 8, 7, 6
- Programmable Additive Latency: 0, CL - 2, or CL - 1 clock
- 8-bit pre-fetch
- Burst Length: 8 (Interleave without any limit, sequential with starting address "000" only), 4 with tCCD = 4 which does not allow seamless read or write [either on the fly using A12 or MRS]
- Bi-directional Differential Data Strobe
- Internal(self) calibration : Internal self calibration through ZQ pin (RZQ : 240 ohm ± 1%)
- On Die Termination using ODT pin
- Average Refresh Period 7.8us at lower than TCASE 85°C, 3.9us at 85°C < TCASE ≤ 95°C
- Asynchronous Reset
- PCB : Height 1.180" (30.00mm), double sided component

Continued >>

MODULE DIMENSIONS



FOR MORE INFORMATION, GO TO WWW.KINGSTON.COM/HYPERX

All Kingston products are tested to meet our published specifications. Some motherboards or system configurations may not operate at the published HyperX memory speeds and timing settings. Kingston does not recommend that any user attempt to run their computers faster than the published speed. Overclocking or modifying your system timing may result in damage to computer components.